The ATLAS High-Granularity Timing Detector

Sabrina Sacerdoti on behalf of the HGTD group

Laboratoire de l'Accelerateur Lineaire

11th Workshop on Picosecond-timing Detectors for Physics and Medical Applications Torino, May 17th





Contents

- 1. Motivation
- 2. The HGTD
- 3. Time Resolution
- 4. Developments in LGAD+ASIC
 - Sensors
 - Electronics
- 5. Summary

Motivation

- Increased luminosity at the HL-LHC:
 - expected $\langle \mu \rangle = 200$
 - average interaction density ~ 1.8 vtx/mm
- With the design z₀ resolution, several vertexes could be merged
- Adding an additional dimension (4D) to existing detectors can provide a new handle on increased interactions per mm



The High-Granularity Timing Detector

The HGTD will provide time measurements for objects in the forward regions of the ATLAS detector



The High-Granularity Timing Detector

The HGTD will provide time measurements for objects in the forward regions of the ATLAS detector



The HGTD: timing in ATLAS

General parameters:

- ▶ 2.4 < |η| < 4.0</p>
- Active area 6.3 m² (total)
- \blacktriangleright Design based on 1.3 \times 1.3 $\rm mm^2$ silicon pixels (2 \times 2 $\rm cm^2$ sensors)
- Radiation hardness up to 4.5 10¹⁵ n_{eq}/cm² and 4.5 MGy
- Number of hits per track:
 - ▶ 2 in 2.4 < |η| < 3.1</p>
 - ▶ 3 in 3.1 < |η| < 4.0</p>

Goal:

- Provide minimum bias trigger
- Instantaneous and unbiased luminosity measurement
- Resolve close by vertices
 - ► small timing resolution (~few 10s of picoseconds).

Contributions to the timing resolution:

$$\sigma_{T}^{2} = \sigma_{L}^{2} + \sigma_{TW}^{2} + \sigma_{jitter}^{2} + \sigma_{clock}^{2}$$

• σ_L Landau fluctuations in the deposited charge in the sensors

Contributions to the timing resolution:

$$\sigma_{T}^{2} = \sigma_{L}^{2} + \sigma_{TW}^{2} + \sigma_{jitter}^{2} + \sigma_{clock}^{2}$$

- σ_L Landau fluctuations in the deposited charge in the sensors
- $\sigma_{TW}^2 = [\frac{V_{th}}{S/t_{rise}}]_{RMS} \propto [\frac{N}{dV/dt}]_{RMS}$



- Variations due to differences in the amplitude of the signal.
- Expected to be negligible after applying an offline correction based on measuring the TOT.

Contributions to the timing resolution:

$$\sigma_{T}^{2} = \sigma_{L}^{2} + \sigma_{TW}^{2} + \sigma_{jitter}^{2} + \sigma_{clock}^{2}$$

- σ_L Landau fluctuations in the deposited charge in the sensors
- $\sigma_{TW}^2 = [\frac{V_{th}}{S/t_{rise}}]_{RMS} \propto [\frac{N}{dV/dt}]_{RMS}$
- $\sigma_{jitter}^2 = \frac{N}{dV/dt} \sim \frac{t_{rise}}{S/N}$



Variations due to noise in the signal

Contributions to the timing resolution:

$$\sigma_{T}^{2} = \sigma_{L}^{2} + \sigma_{TW}^{2} + \sigma_{jitter}^{2} + \sigma_{clock}^{2}$$

• σ_L Landau fluctuations in the deposited charge in the sensors

• $\sigma_{TW}^2 = [\frac{V_{th}}{S/t_{rise}}]_{RMS} \propto [\frac{N}{dV/dt}]_{RMS}$

•
$$\sigma_{jitter}^2 = \frac{N}{dV/dt} \sim \frac{t_{rise}}{S/N}$$

- σ_{clock}^2 contribution from the clock distribution
 - High Frequency: bunch to neighbouring bunch
 - Low frequency: drift (over periods of ~ 1ms)
 - Expected to be below 10 ps

Contributions to the timing resolution:

$$\sigma_{T}^{2} = \sigma_{L}^{2} + \sigma_{TW}^{2} + \sigma_{jitter}^{2} + \sigma_{clock}^{2}$$

• σ_L Landau fluctuations in the deposited charge in the sensors

•
$$\sigma_{TW}^2 = [\frac{V_{th}}{S/t_{rise}}]_{RMS} \propto [\frac{N}{dV/dt}]_{RMS}$$

•
$$\sigma_{jitter}^2 = \frac{N}{dV/dt} \sim \frac{t_{rise}}{S/N}$$

• σ_{clock}^2 contribution from the clock distribution < 10 ps

Additional contributions from TDC and t_0 calibration are expected to be negligible.

Low Gain Avalanche Diode

LGADs are n-on-p planar silicon detectors:

- low internal gain (lower noise amplification)
- radiation hardness
- excellent timing resolution





- Gain is independent of the thickness
- Thinner pads/larger gain give smaller rise times
- 50 μ m is baseline and 35 μ m under study
- Radiation damage can be controlled with cooling (-30°C)



Overview of test beam results

- Several test beam campaigns since 2016 (sensors from CNM and HPK).
- Achieved time resolution below 30 ps

CNM - 45 μ m thick single pads¹



 σ_t vs gain

- Strong decrease of σ_t with V_{bias} ($\sigma_t < 30$ ps at 235/320 V in non-irrad. sensors)
- Irradiated sensors tested at different temperatures.
- Decrease of σ_t with gain. Studies point to a safe gain of 10-20.

¹results from J. Lange et al.; similar results in sensors from FBK

Overview of test beam results: time resolution

- September 2017 test beam with 120 GeV pions at CERN-SPS
- CNM 2 \times 2 arrays, each pad 1.063 \times 1.063 mm²
- Test-beam 2016 paper available in in arxiv



Overview of test beam results: efficiency

- CNM 2 × 2 arrays, each pad 1.063 × 1.063 mm²
- September 2017 test beam with 120 GeV pions at CERN-SPS



- Negligible inefficiency in the centre of the pads.
- Interpad area is not a dead region
- Also: cross-talk mostly negligible/~ 5% in irradiated sensors

ALTIROC ASIC

- $\blacktriangleright\,$ HGTD design is to have sensors of 225 pixels (1.3 $\times\,1.3\,{\rm mm^2})$
- Will be read out by an ASIC, bump-bonded to the sensor
 - Should keep the excellent time resolution of the LGADs, σ_{el} < 25 ps</p>
 - ▶ Power consumption constrained by cooling power (sensors at -30 °C)
 - Current status:
 - ALTIROC0_v1: analog single pixel
 - ALTIROC0_v2: test bench studies are starting
 - layout of single channel readout is finished, post-layout simulations ongoing
 - off-pixel design is ongoing (mainly phase-shifter and luminosity data formatting unit)
 - will submit a 5 \times 5 version (ALTIROC1) in June





Single channel: preamplifier + discriminator

- ► Rise time optimised to match drift time of sensor (~ 0.5 1ns) to minimise jitter
- Voltage/VPA and transimpedance/TZ have been implemented in simulation
- TOT excursion of the TZ is much shorter, and jitter is higher
- Simulated/measured jitter in VPA below 15/25 ps for 1 MIP



A fixed threshold discriminator will be used to measure the TOA. Time walk will be corrected through the measurement of the TOT.

Single pixel TDC

- Vernier delay line configuration with a reverse START-STOP scheme for power saving
- TOA-TDC: 2.5 ns range, 20 ps bin
- TOT-TDC: 5/20 ns range, 20/40 ps bin (TZ/VPA)
- Maximum conversion time of 25/28 ns for the TOA/TOT TDCs (preliminary sim.).



Single pixel memory

Temporarily store hit data and select hits associated to a trigger.



Baseline design is to use full buffering, storing TOA+TOT/hit flag:

- ► Handle 10/35µs latency for L0/L1 trigger
- ▶ 1 memory position per BC: 1400 × 17 bits depth
- Simulation of 400 × 17 SRAM, assuming 10% occupancy gives a power consumption of 57.2µW
- A 1400 depth memory would need to be split in several banks, yielding a power consumption 1.5/2 times larger

Off-pixel electronics - Luminosity

- *L* is linearly proportional to *N_{hits}*
- Non-linearities arise from:
 - double hits \rightarrow low occupancy
 - ▶ background noise (afterglow)→ compare N_{hits} in a smaller and wider time window around the BC



- Two time windows, W2>W1
- Rising and falling edges of both windows are tunable
- Transmit the sum of hits per ASIC for each BC
- Only for ASICs at R > 320 mm
- The sum over ASICs is computed in 64 regions and saved.

Off-pixel electronics - Phase shifter

The inner clocks of the ASIC have to be in phase, with an accuracy \sim 100ps, in order to:

- ensure the correct time conversion of the TDC
- correctly adjust the time windows necessary to measure the luminosity Characteristics:
 - Receives clocks at 40, 320 and 640 MHz from the PLL
 - Output phase adjusted to a step smaller than 100 ps
 - Additional jitter below 5 ps
 - Estimated power consumption around 10 mW
 - Design is ongoing



Summary

- The HGTD is a Phase-II upgrade ATLAS project that will provide timing capability in the forward region.
- The detector layout has converged to a compromise between spatial/monetary constrains and the goal to guarantee 3 hits per track for smaller radius (high η).
- Next steps:
 - Tests of single pixel readout will continue this year with sensors+ALTIROC0_v2 (2x2 pads)
 - Testing different methods to improve radiation hardness in sensors
 - Arrays of 5 × 5 pixels will be ready in summer 2018
 - Submission of ALTIROC1 foreseen in June 2018
 - Extensive testing to be done through Q4 2018/Q1 2019, including test bench measurements of the sensor bump bonded to the ASIC
- Approval status:
 - technical proposal approved internally by ATLAS in April
 - approval by LHCC is expected in summer
 - delivery of TDR should be in Q1 2019

BACK UP

Pixel Size

The definition of the size of the pixel is a result of several considerations, mainly:

- The need to keep occupancy low (below 10%)
- A small detector capacitance reduces noise, $C = \epsilon_r \epsilon_0 A / w$



Voltage/Transimpedance preamplifier: schematics

Voltage Preamplifier



Transimpedance Preamplifier





- Difference btw measurement and simulated jitter attributed to different noise
- Lower jitter in v2
- Jitter in TZ larger than in VPA

Voltage/Transimpedance preamplifier: pulse simulation



TZ preamplifier gives a faster, lower amplitude pulse than VPA.

ALTIROC ASIC schematic

